

Filename: PMP5711REVC_BILLOFMATERIALS_bom.xls						
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PMP5711REVC_BILLOFMATERIALS BOM						
COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	DNP	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H103K	TDK
1	C2	100uF	Capacitor, Aluminum, 80V, ±20%	0.543 x 0.543	EEVFK1K101Q (H13)	Panasonic
1	C16	100nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
1	C19	100uF	Capacitor, Aluminum, 25V, 20%	0.260 x 0.276 inch	EEEFKE101XAP	Panasonic
1	C22	1nF	Capacitor, Ceramic, 2kV, C0G, 10%	1812	Std	Std
1	C23	47nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H333K	TDK
1	C24	330pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H221K	TDK
1	C27	10nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C29	33nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C31	DNP	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C474M	TDK
1	C32	4.7uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
5	C10 C15 C20-21 C30	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C105M	TDK
1	C101	10nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H103K	TDK
2	C103-104	1nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
2	C105-106	1nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H221K	TDK
2	C11 C33	33nF	Capacitor, Ceramic, 250-V, X7R	1206	C3216X7R2E333M	TDK
2	C17-18	47pF	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
2	C25 C102	10nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H221K	TDK
2	C28 C26	DNP	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
5	C3-7	2.2uF	Capacitor, Ceramic, 100-V, X7R, 20%	1210	C3225X7R2A225M	TDK
2	C8 C12	820uF	Capacitor, OSCON, 6.3V, 12milliohm, 20%	8.3mm (E12)	6SVPC820M	Sanyo
3	C9 C13-14	22uF	Capacitor, Ceramic, 16-V, X7R, 20%	1210	Std	Std
1	D1	DNP	Diode, Rectifier, 1A, 40V	SMA	MBRA140	ON Semiconductor
1	D3	MBRS540T3	Diode, Schottky, 5-A, 40-V	SMC	MBRS540T3	On Semi
1	D11	OPEN	Diode, Switching, 100-V, 200-mA, 225-mW	SOD-123	MMSD914T1	On Semi
2	D2 D9	BAT54	Diode, Schottky, 200-mA, 30-V	SOT23	BAT54	Vishay-Liteon
4	D4 D6-8	MMSD914	Diode, Switching, 100-V, 200-mA, 225-mW	SOD-123	MMSD914T1	On Semi
2	D5 D10	6.8V	Diode, Zener, 6.8-V	SOT23	BZX84C6V8LT1	ON Semiconductor
3	J1-3	ED1609-ND	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	ED1609	OST
1	L1	2.2 uH	Inductor, SMT, 35A, ±10%	26.00 X 27.00 mm	55880	Payton
1	L2	1mH	Inductor, SMT, 0.1A, 14ohm	0.26x0.09 inch	DO1608C-105ML	Coilcraft
1	Q3	Si7815DN	MOSFET, Fast Switching, PChan, -150V, -8.9A, 295 milliOhm	PWRPAK 1212	Si7815DN	Vishay
1	Q7	MMBT3904LT1G	Trans, NPN, xx-V, yy-mA, zz-W	SOT23	MMBT3904LT1	On Semi
1	Q8	MMBT3906LT1G	Trans, PNP, xx-V, yy-mA, zz-W	SOT23	MMBT3906LT1	On Semi
4	Q1-2 Q10-11	CSD17312Q5	MOSFET, N-Chan, 30V, 100A, typ. 1.4 milli-ohm	QFN-8 POWER	CSD17312Q5	TI
2	Q4-5	BSC360N15NS3G	MOSFET, Nch, 150V, 15nC, 36 milliohm	TDSON-8	BSC360N15NS3G	Infineon

2	Q6 Q9	FZT651	Transistor, NPN, VCE 60V, 3A	SOT223	FZT651	Diodes Inc
1	R1	DNP	Resistor, 1W, 5%	2512	STD	STD
1	R3	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R6	3.3	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	R7	3.65k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R9	1.78k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R11	11.3k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R15	1 MEG	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R16	50k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R25	3.01k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R26	DNP	Do Not Populate	0603	N/A	N/A
1	R29	499	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R30	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R33	249	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R101	2.2	Resistor, 1W, 5%	2512	STD	STD
2	R14 R12	90.9k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R17 R28	2.49k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	R19 R24 R32 R102	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	R2 R13 R21-22	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R23 R18	4.99k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R27 R20 R31	DNP	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R4-5	1k	Resistor, Chip, 1/16W, 5%	0805	Std	Std
2	R8 R10	100k	Resistor, Chip, 1/10W, 1%, 100V	0805	Std	Std
1	T1	PA1005.100NL	XFMR, Current Sense	0.284 x 0.330 inch	PA1005.100NL	Pulse
1	T2	100 uH	Transformer, 175W SMPS ±16%	26x30mm	55879	Payton
1	TP7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	240-345	Keystone
6	TP1 TP3 TP5-6 TP9-10	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
4	TP2 TP4 TP8 TP11	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	UCC2897APW	IC, Current-Mode Active Clamp PWM Controller	PW20	UCC2897APW	Texas Instruments
1	U2	TL103WAID	IC, Dual OpAmp With Internal Reference	SO8	TL103WAID	TI
1	U3	TCMT1107	IC, Photocoupler, CTR = 80% - 160%	MF4	TCMT1107	Vishay
Notes:						
	1. These assemblies are ESD sensitive, ESD precautions shall be observed.					
	2. These assemblies must be clean and free from flux and all contaminants.					
	Use of no clean flux is not acceptable.					
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.					
	4. Ref designators marked with an asterisk (***) cannot be substituted.					
	All other components can be substituted with equivalent MFG's components.					

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